Vacuum Reflow Oven

VSU 20

Heated Area: Ø200mm

Max. Temperature: 400°C

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VACUUM SOLDER REFLOW SYSTEMS

Overview

Oven with aluminum chuck hotplate, ceramic coated on top side,

1x thermocouple fixed in chuck and up to 3x freely possitional or fixed in chamber lid,

Integrated water chiller, Compact design, Single phase power supply,

Cooling under vacuum by means of a lifting cold plate, Very low nitrogen consumption.

Ebedded controller with 7” touch display and PC windows based application.

Specifications

Process environment	nitrogen, inert gas, formic acid
Heated area	Ø260mm
Clearance above heater plate	45 mm
Maximum temperature	400°C continuous operation
Ramp heat up / cool down	120-150°C/min
Control deviation	+/- 0.5°C
Heating / cooling type	resistive heating / lifting cold plate
Temperature measurement	4x thermocouples K-Type
Vacuum measurement	integrated absolute vacuum gauge down to 5 mbar
Maximum vacuum	5x10-4 mbar
Leak test of entire system	< 5 x 10-8 mbar.l/s Helium
Formic acid bubbler	40 ml container, integrated in front panel
Chamber lid	manual closing/opening with lid lock, weight balanced
Gas supply	nitrogen 5 bar(abs) at line 1-3, compr. air 5-8bar(abs)
Chamber cooling	water cooling with integrated chiller
Dimensions	550 mm(W) x 615 mm(D) x 400 mm(H) with closed lid
Weight	35 kg
Power supply	1 phase / 190-240V, 50/60 Hz

Optional

auto refill for formic acid	3-color signalization
additional gas line	mounting rack with place for pump
higher clearance above heating plate	vacuum pumps
down to 5x10-4 vacuum measurement	

INVACU Ltd.
Burgas, Odrin 15 st., 8000, Bulgaria
tel.: +359 56 813631
info@invacu.com